

Title (en)

Palladium alloy electroplating process.

Title (de)

Palladiumlegierung-Elektroplattierungsverfahren.

Title (fr)

Procédé de dépôt électrolytique d'un alliage de palladium.

Publication

EP 0415632 A1 19910306 (EN)

Application

EP 90309166 A 19900821

Priority

US 40020289 A 19890829

Abstract (en)

An electroplating process is described for electroplating alloys of palladium and arsenic. The resulting electrodeposits are bright, ductile and remain ductile and crack-free even when the electrodeposits are quite thick. The deposits are quite hard and suitable for contact surfaces particularly in situations where wear characteristics require thick deposits. The electroplating process is also useful for making articles such as bellows by electroform procedures particularly since the electroplated material has extraordinary physical properties (good resilience, low stress and ductility) as well as good corrosion resistance.

IPC 1-7

C25D 3/56

IPC 8 full level

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CPC (source: EP KR)

C25D 3/50 (2013.01 - KR); **C25D 3/567** (2013.01 - EP)

Citation (search report)

- [AD] US 4486274 A 19841204 - ABYS JOSEPH A [US], et al
- [X] CHEMICAL ABSTRACTS, vol. 107, no. 26, 28th December 1987, page 553, abstract no. 245119b, Columbus, Ohio, US; S. CHIDA et al.: "Electrodeposition of amorphous palladium-arsenic alloy films from ethylenediamine-palladium(II) complex solution", & KINZOKU HYOMEN GIJUTSU 1987, 38(10), 478-82

Designated contracting state (EPC)

CH DE FR GB IT LI NL SE

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